LE24CBK23MC

CMOS IC

Dual port EEPROM
Two Wire Serial Interface
(2K+2K EEPROM)

Overview

The dual port EEPROM series consists of two independent banks, and each bank can be controlled separately using dedicated control pins. The two banks can each be controlled separately, but share the internal power supply system. In addition, this product uses a 2-wire serial interface, and is the optimal device for realizing substantial reductions in system cost and mounting area, as well as low power consumption.

This product also incorporates a combine mode that allows the two-bank configuration (2K bits + 2K bits) to be used as a pseudo-one-bank configuration (4K bits) by setting the COBM# pin to the low level. Together with the 16-byte page write function, this enables a reduction in the number of factory write processes.

This product incorporates high performance CMOS EEPROM technology and realizes high-speed operation and high-level reliability. The interface of this product is compatible with the I^2C bus protocol, making it ideal as a nonvolatile memory for small-scale parameter storage.

In addition, this product also supports DDC2^{TM}, so it can also be used as an EDID data storage memory for display equipment.

Functions

- Capacity   : 2K bits (256 × 8 bits) + 2K bits (256 × 8 bits): 4k bits in total
- Bank configuration   : 2-Bank (2k-bit + 2k-bit)
- Single supply voltage   : 2.5V to 5.5V
- Interface   : Two wire serial interface (I^2C Bus*), VESA DDC2^{TM} compliant**
- Operating clock frequency : 400kHz (max)
- Low power consumption   : Standby: 5μA (max)
                               : One-bank read: 0.8 mA (max.)
- Automatic page write mode : 16 bytes
- Read mode   : Sequential read and random read
- Erase/Write cycles   : 10^6 cycles
- Data Retention   : 20 years
- Default data   : FFh(All address)
- High reliability   : Adopts proprietary symmetric memory array configuration
                                 (USP6947325)
                                 Noise filters connected to SCL1, SDA1, SCL2 and SDA2 pins
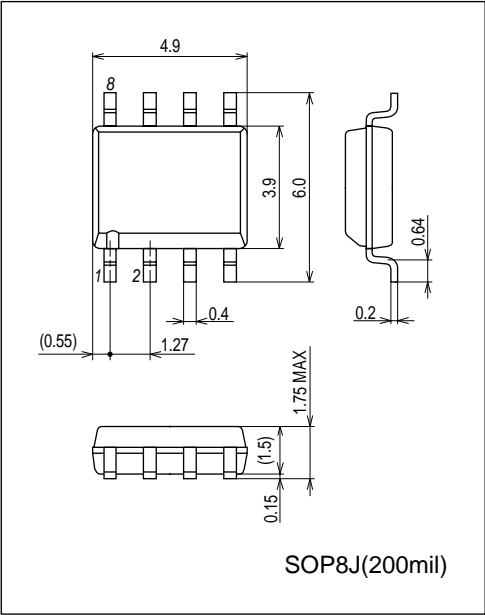   Incorporates a feature to prohibit write operations under low voltage conditions.

  * : I^2C Bus is a trademark of Philips Corporation.
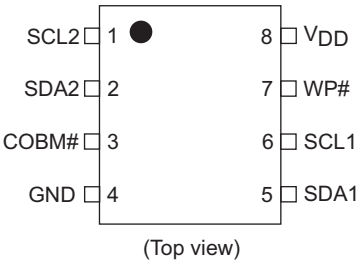 ** : DDC and EDID are trademarks of Video Electronics Standard Association (VESA).

Package Dimensions

unit:mm (typ)

3434

SOP8J(200mil)

Pin Assignment

SCL2 □ 1 ●   8 □ V_DD

SDA2 □ 2   7 □ WP#

COBM# □ 3   6 □ SCL1

GND □ 4   5 □ SDA1

(Top view)

Pin Descriptions

PIN.1	SCL2	Clock input	Bank2
PIN.2	SDA2	Data input/output	
PIN.3	COBM#	Bank/Combine mode change	
PIN.4	GND	Ground	
PIN.5	SDA1	Data input/output	Bank1
PIN.6	SCL1	Clock input	
PIN.7	WP#	Write protection	
PIN.8	V_DD	Power supply	

Block Diagram
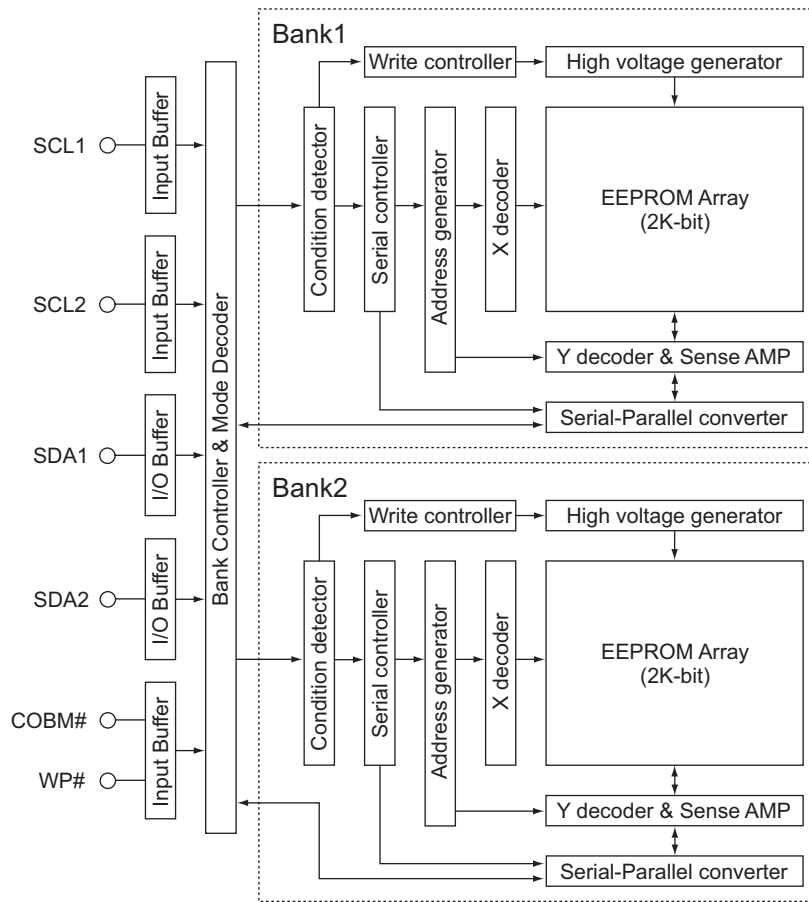
Description of Operation

The Bank1 control signals are SCL1 and SDA1, and the Bank2 control signals are SCL2 and SDA2. The control signals for each bank can be controlled separately, regardless of the other bank's status. This enables the product to be handled like two separate EEPROM mounted in a single package, which means that the Bank1 and Bank2 sides can be used simultaneously for two independent systems.

Bank mode (2K bits + 2K bits) and combine mode (internally handled as 4K bits) can be switched using the COBM# pin. In combine mode, the Bank1 control signals (SCL1, SDA2) are used, and both Bank1 and Bank2 are accessed. This enables the two-bank configuration (2K bits + 2K bits) to be used as a pseudo-one-bank configuration (4K bits), which allows access to both the Bank1 and Bank2 areas using a single system of control signals (SCL1, SDA1). Data correlation is guaranteed between combine mode and bank mode, enabling operation while switching the mode, such as performing write in combine mode and read in bank mode.

Specifications

Absolute Maximum Ratings

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage			-0.5 to +6.5	V
DC input voltage			-0.5 to +5.5	V
Over-shoot voltage		Below 20ns	-1.0 to +6.5	V
Storage temperature	Tstg		-65 to +150	°C

Note: If an electrical stress exceeding the maximum rating is applied, the device may be damaged.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Operating Conditions

Parameter	Symbol	Conditions	Ratings	Unit
Operating supply voltage			2.5 to 5.5	V
Operating temperature			-40 to +85	°C

DC Electrical Characteristics

Parameter	Symbol	Conditions	V_{DD}=2.5V to 5.5V min	typ	max	Unit
Supply current at reading (when either Bank1 or Bank2 is read)	$I_{CC}11$	f=400kHz			0.8	mA
Supply current at reading (when both Bank1 and Bank2 are read simultaneously)	$I_{CC}12$	f=400kHz			1.6	mA
Supply current at writing (when either Bank1 or Bank2 is write)	$I_{CC}21$	f=400kHz, t_{WC}=5ms			5	mA
Supply current at writing (when both Bank1 and Bank2 are write simultaneously)	$I_{CC}22$	f=400kHz, t_{WC}=5ms			8	mA
Standby current	I_{SB}	V_{IN}=V_{DD} or GND		0.7	5	μA
Input leakage current	I_{LI}	V_{IN}=GND to V_{DD}	-2.0		+2.0	μA
Output leakage current (SDA)	I_{LO}	V_{OUT}=GND to V_{DD}	-2.0		+2.0	μA
Input low voltage	V_{IL}				V_{DD}*0.3	V
Input high voltage	V_{IH}		V_{DD}*0.7			V
Input low voltage(WP# pin)	V_{IL_WP}	V_{DD} < 4.0V			V_{DD}*0.2	V
Input high voltage(WP# pin)	V_{IH_WP}	*1)	V_{DD}*0.7			V
Output low level voltage	V_{OL}	I_{OL}=0.7mA, V_{DD}=2.5V			0.2	V
		I_{OL}=3.0mA, V_{DD}=2.5V			0.4	V
		I_{OL}=3.0mA, V_{DD}=5.5V			0.4	V
		I_{OL}=6.0mA, V_{DD}=4.5V			0.6	V

*1: The actual V_{IH} value of the WP# pin is 2.0V (V_{DD} = 5.0V).

Capacitance/Ta=25°C, f=100kHz

Parameter	Symbol	Conditions	min	typ	max	Unit
In/Output capacitance	$C_{I/O}$	$V_{I/O}$=0V (SDA)		2	5	pF
Input capacitance	C_I	V_{IN}=0V (Other SDA)		2	5	pF

Note: This parameter is sampled and not 100% tested.

AC Electric Characteristics

Fast Mode

Parameter	Symbol	V_{DD}=2.5V to 5.5V			unit
		min	typ	max	
Slave mode SCL clock frequency	f_{SCLS}			400	kHz
SCL clock low time	t_{LOW}	1200			ns
SCL clock high time	t_{HIGH}	600			ns
SDA output delay time	t_{AA}	100		900	ns
SDA data output hold time	t_{DH}	100			ns
Start condition setup time	$t_{SU.STA}$	600			ns
Start condition hold time	$t_{HD.STA}$	600			ns
Data in setup time	$t_{SU.DAT}$	100			ns
Data in hold time	$t_{HD.DAT}$	0			ns
Stop condition setup time	$t_{SU.STO}$	600			ns
SCL, SDA rise time	t_R			300	ns
SCL, SDA fall time	t_F			300	ns
Bus release time	t_{BUF}	1200			ns
Noise suppression time	t_{SP}			100	ns
Write cycle time	t_{WC}			5	ms

Standard Mode

Parameter	Symbol	V_{DD}=2.5V to 5.5V			unit
		min	typ	max	
Slave mode SCL clock frequency	f_{SCLS}			100	kHz
SCL clock low time	t_{LOW}	4700			ns
SCL clock high time	t_{HIGH}	4000			ns
SDA output delay time	t_{AA}	100		3500	ns
SDA data output hold time	t_{DH}	100			ns
Start condition setup time	$t_{SU.STA}$	4700			ns
Start condition hold time	$t_{HD.STA}$	4000			ns
Data in setup time	$t_{SU.DAT}$	250			ns
Data in hold time	$t_{HD.DAT}$	0			ns
Stop condition setup time	$t_{SU.STO}$	4000			ns
SCL, SDA rise time	t_R			1000	ns
SCL, SDA fall time	t_F			300	ns
Bus release time	t_{BUF}	4700			ns
Noise suppression time	t_{SP}			100	ns
Write cycle time	t_{WC}			5	ms

Bus Timing
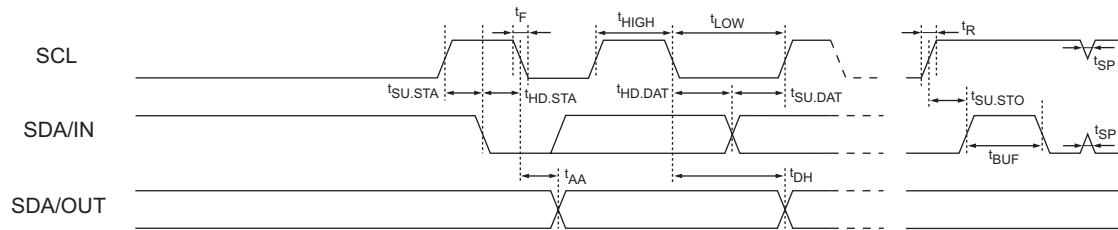
Write Timing
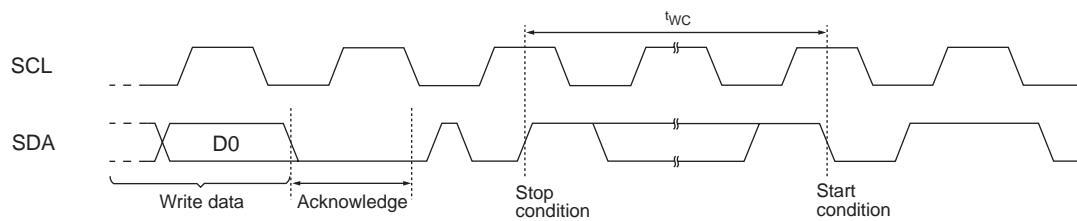
Pin Functions

(Bank1)

SCL1 (serial clock input) pin

  The SCL1 pin is the serial clock input pin used to access the Bank1 area, and processes signals at the rising and falling edges of the SCL1 clock signal.

  This pin must be pulled up by a resistor to the V_{DD} level, and wired-ORed with another open drain (or open collector) output device for use.

   In combine mode, the SCL1 pin functions as the serial clock input pin that controls both Bank1 and Bank2

SDA1 (serial data input/output) pin

  The SDA1 pin is used to transfer serial data to the input/output of the Bank1 side area and it consists of a signal input pin and n-channel transistor open drain output pin.

  Like the SCL1 line, the SDA1 line must be pulled up by a resistor to the V_{DD} level and wired-ORed with another open drain (or open collector) output device for use.

(Bank2)

SCL2 (serial clock input) pin

  The SCL2 pin is the serial clock input pin used to access the Bank2 area, and processes signals at the rising and falling edges of the SCL2 clock signal.

  This pin must be pulled up by a resistor to the V_{DD} level, and wired-ORed with another open drain (or open collector) output device for use.

  In combine mode, the SCL2 pin is invalid.

SDA2 (serial data input/output) pin

  The SDA2 pin is used to transfer serial data to the input/output of the Bank2 side area and it consists of a signal input pin and n-channel transistor open drain output pin.

  Like the SCL2 line, the SDA2 line must be pulled up by a resistor to the V_{DD} level and wired-ORed with another open drain (or open collector) output device for use.

(Common pin)

WP# (Write protection) pin

  When the WP# pin is at the low level, write protection is enabled, and write is prohibited to all memory areas within both Bank1 and Bank2. Read operation can access all memory areas regardless of the WP# pin status.

COBM# (Combine mode) pin

  The COBM# pin is used to switch the EEPROM internal operation between bank mode and combine mode. The EEPROM operates in bank mode when the COBM# pin is at the high level, and in combine mode when at the low level. Note that in combine mode, the SCL2 and SDA2 pins are handled as don't care.

Functional Description

1. Start condition

When the SCL line is at the high level, the start condition is established by changing the SDA line from high to low. The operation of the EEPROM as a slave starts in the start condition.

2. Stop condition

When the SCL line is at the high level, the stop condition is established by changing the SDA line from low to high. When the device is set up for the read sequence, the read operation is suspended when the stop condition is received, and the device is set to standby mode. When it is set up for the write sequence, the capture of the write data is ended when the stop condition is received, and the EEPROM internal write operation is started.
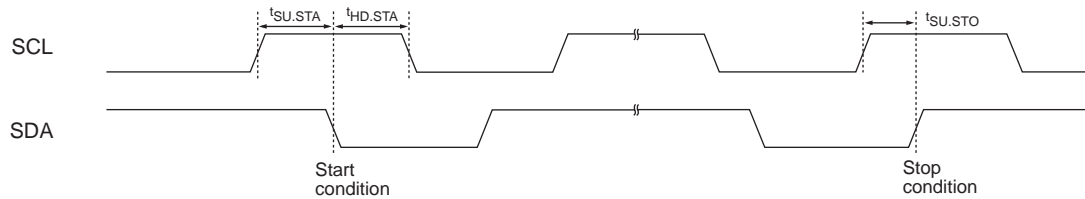
3. Data transfer

Data is transferred by changing the SDA line while the SCL line is low. When the SDA line is changed while the SCL line is high, the resulting condition will be recognized as the start or stop condition.
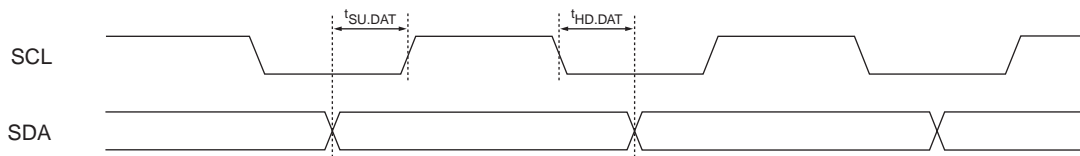
4. Acknowledge

During data transfer, 8 bits are transferred in succession, and then in the ninth clock cycle period the device on the system bus receiving the data sets the SDA line to low, and sends the acknowledge signal indicating that the data has been received. The acknowledge signal is not sent during an EEPROM internal write operation.
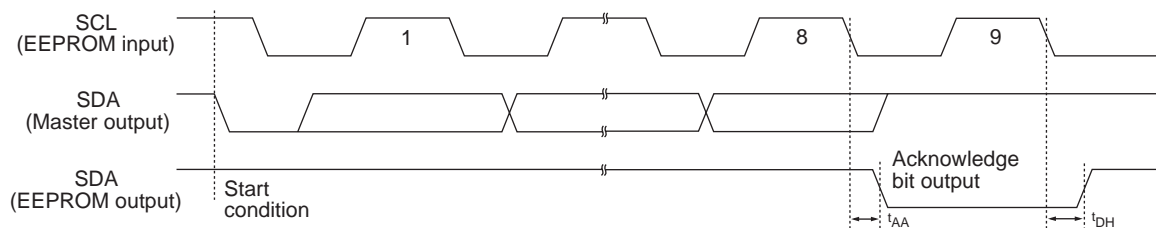
5. Device addressing

  For the purposes of communication, the master device in the system generates the start condition for the slave device.
  Communication with a particular slave device is enabled by sending along the SDA bus the device address, which is 7
  bits long, and the read/write command code, which is 1 bit long, immediately following the start condition.
   The upper four bits of the device address are called the device codes which, for this product, are fixed at "1010".
   The LE24CBK23MC has internal 3-bit slave addresses (Bank1: SA2 and SA1, Bank2: SB2 and SB1) following the
   device code, and the default slave addresses are set to SA0 = 0, SA1 = 0, SA2 = 0 and SB0 = 0, SB1 = 0, SB2 = 0,
   respectively.

  When the device code + slave address input from SDA are compared with this product's device code and the slave
  address set during mounting and are found to match them, this product sends back the acknowledge signal in the
  ninth clock cycle period, and performs the read or write operation in accordance with the read or write command
  code. When there is no match, the EEPROM enters standby mode. When executing a read operation immediately
  after switching the slave device, the random read command should be used.
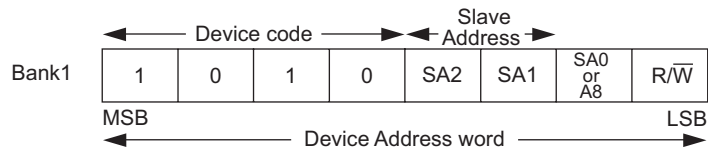
  - The default internal slave address is set to SA2 = 0, SA1 = 0, SA0 = 0.
  - In bank mode (2K bits), the effective address bits are A7 to A0, and the effective slave address bits are SA2, SA1
    and SA0.
  - In combine mode (2K bits + 2K bits), the effective address bits are A8 to A0, and the slave address bits SA2 and
    SA1 are don't care.
        A8 = 0: Selects the Bank1 area,; A8 = 1: Selects the Bank2 area.

	Effective address	Slave address
Bank mode (COBM# = "H")	A7 – A0	SA2, SA1, SA0
Combine mode (COBM# = "L")	A8 – A0 A8 = 0: 1 bank selection area A8 = 1: 2 bank selection area	SA2, SA1 But SA2 and SA1 are Don't care
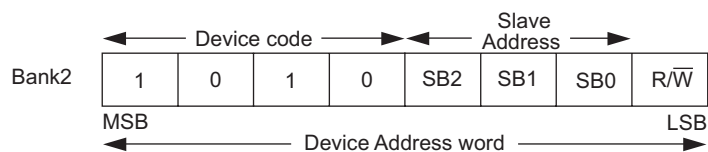
  - In combine mode (2K bits + 2K bits), Bank2 communication is invalid.

|	Effective address	Slave address
Bank mode (COBM# = "H")	A7 – A0	SB2, SB1, SB0
Combine mode (COBM# = "L")	-	-

6 Internal mode

The EEPROM functions in bank mode when the COBM# pin is at the high level, and in combine mode when the COBM# pin is at the low level.

6-1. Bank mode

The EEPROM functions in bank mode when the COBM# pin is at the high level. In bank mode, each bank (Bank1, Bank2) is controlled separately using dedicated control signals. The two banks are independent, and can be controlled separately regardless of the other bank's status.

This enables the EEPROM to be handled as two independent EEPROM devices incorporated in a single package. In turn, this makes it possible for the Bank1 and Bank2 sides to be connected to the MCU of separate systems.
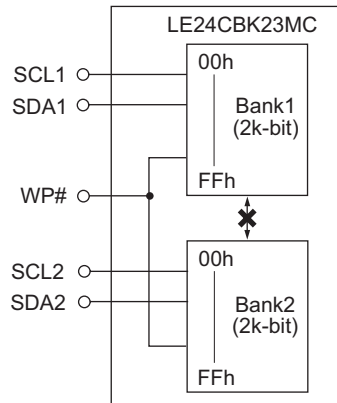
6-2. Combine mode

The EEPROM functions in combine mode when the COBM# pin is at the low level. In combine mode, the Bank1 control signals (SCL1, SDA1) are used to control both Bank1 and Bank2. Combine mode uses the two-bank configuration (2K bits + 2K bits) as a pseudo-one-bank configuration (4K bits). In combine mode, the Bank2 control signals (SCL2, SDA2) are handled as don't care.
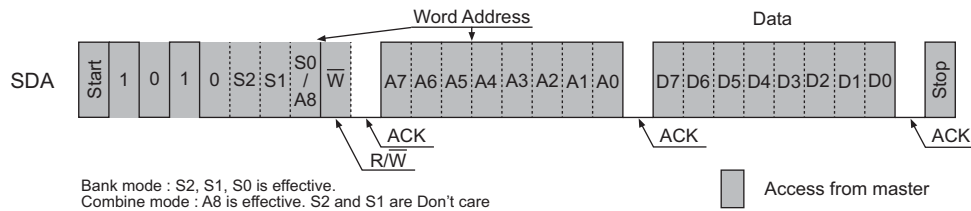
In combine mode the memory area is processed as a single 4K-bit bank, so the address MSB changes from A7 to A8, and A8 becomes an effective address bit. Set A8 = 0 to control the Bank1 area, or A8 = 1 to control the Bank2 area. Data correlation is guaranteed between combine mode and bank mode, enabling operation while switching the mode, such as performing write in combine mode and read in bank mode.
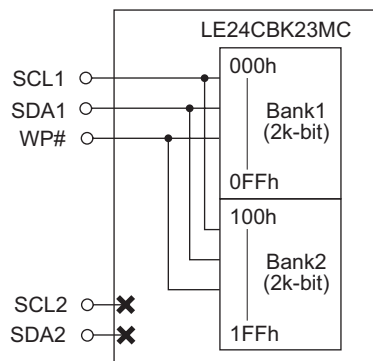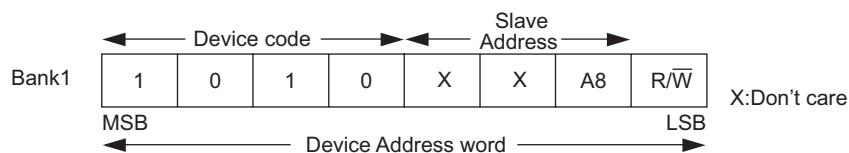
7 EEPROM write operation
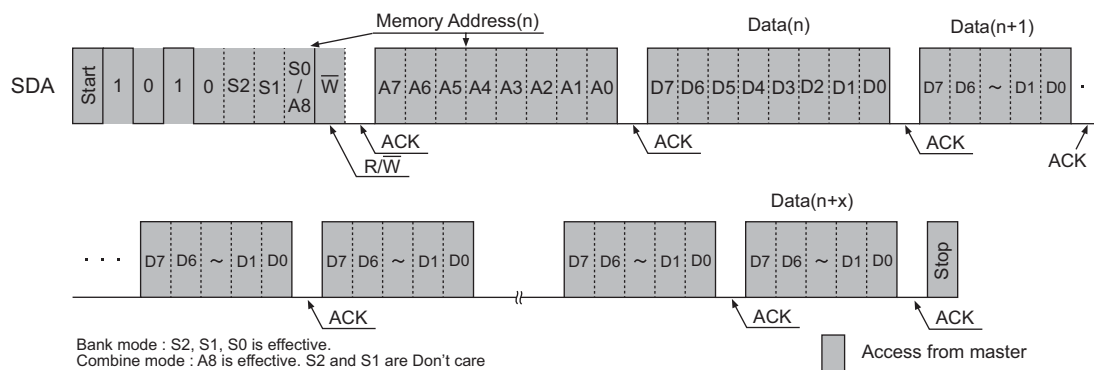
7-1. Byte writing

When the EEPROM receives the 7-bit device address and write command code "0" after the start condition, it generates an acknowledge signal. After this, if it receives the 8-bit word address, generates an acknowledge signal, receives the 8-bit write data, generates an acknowledge signal and then receives the stop condition, the internal write operation of the EEPROM in the designated memory address will start. Rewriting is completed in the t_{WC} period after the stop condition. During an EEPROM internal write operation, no input is accepted and no acknowledge signals are generated.

Word Address | Data

SDA | Start | 1 | 0 | 1 | 0 | S2 | S1 | S0/A8 | $\overline{W}$ | A7 A6 A5 A4 A3 A2 A1 A0 | D7 D6 D5 D4 D3 D2 D1 D0 | Stop

ACK | ACK | ACK
R/$\overline{W}$

Bank mode : S2, S1, S0 is effective.
Combine mode : A8 is effective. S2 and S1 are Don't care

Access from master

7-2. Page writing

This product enables pages with up to 16 bytes to be written. The basic data transfer procedure is the same as for byte writing: Following the start condition, the 7-bit device address and write command code "0," word address (n), and data (n) are input in this order while confirming acknowledge "0" every 9 bits. The page write mode is established if, after data (n) is input, the write data (n+1) is input without inputting the stop condition. After this, the write data equivalent to the largest page size can be received by a continuous process of repeating the receiving of the 8-bit write data and generating the acknowledge signals.
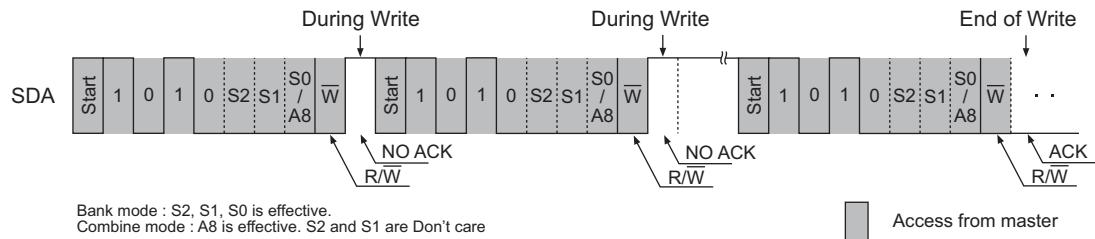
At the point when the write data (n+1) has been input, the lower 4 bits (A0-A3) of the word addresses are automatically incremented to form the (n+1) address. In this way, the write data can be successively input, and the word address on the page is incremented each time the write data is input. If the write data exceeds 16 bytes or the last address of the page is exceeded, the word address on the page is rolled over. Write data will be input into the same address two or more times, but in such cases the write data that was input last will take effect. Finally, the EEPROM internal write operation corresponding to the page size for which the write data is received starts from the designated memory address when the stop condition is received.

Memory Address(n) | Data(n) | Data(n+1)

SDA | Start | 1 | 0 | 1 | 0 | S2 | S1 | S0/A8 | $\overline{W}$ | A7 A6 A5 A4 A3 A2 A1 A0 | D7 D6 D5 D4 D3 D2 D1 D0 | D7 D6 ~ D1 D0

ACK | ACK | ACK | ACK
R/$\overline{W}$

Data(n+x)

D7 D6 ~ D1 D0 | D7 D6 ~ D1 D0 | D7 D6 ~ D1 D0 | D7 D6 ~ D1 D0 | Stop

ACK | ACK | ACK

Bank mode : S2, S1, S0 is effective.
Combine mode : A8 is effective. S2 and S1 are Don't care

Access from master

7-3. Acknowledge polling

Acknowledge polling is used to find out when the EEPROM internal write operation is completed. When the stop condition is received and the EEPROM starts rewriting, all operations are prohibited, and no response can be given to the signals sent by the master device. Therefore, in order to find out when the EEPROM internal write operation is completed, the start condition, device address and write command code are sent from the master device to the EEPROM (slave device), and the response of the slave device is detected.

In other words, if the slave device does not send the acknowledge signal, it means that the internal write operation is in progress; conversely, if it does send the acknowledge signal, it means that the internal write operation has been completed.

Bank mode : S2, S1, S0 is effective.
Combine mode : A8 is effective. S2 and S1 are Don't care

Access from master

8 EEPROM read operations

8-1. Current address reading

The address equivalent to the memory address accessed last +1 is held as the internal address of the EEPROM for both write* and read operations. Therefore, provided that the master device has recognized the position of the EEPROM address pointer, data can be read from the memory address with the current address pointer without specifying the word address.

As with writing, current address reading involves receiving the 7-bit device address and read command code "1" following the start condition, at which time the EEPROM generates an acknowledge signal. After this, the 8-bit data of the (n+1) address is output serially starting with the highest bits. After the 8 bits have been output, by not sending an acknowledge signal and inputting the stop condition, the EEPROM completes the read operation and is set to standby mode.

If the previous read address is the last address, the address for the current address reading is rolled over to become address 0.

* The current address assigned after a page write is the number of bytes written at the designated word address plus 1 if the volume of the write data is greater than 1 byte or less than or equal to 16 bytes, and is the designated word address if the volume of the write data is 16 bytes or more. If the last address of the page (A3 to A0 = 1111b) is specified as the word address for a byte write, the internal address after the write becomes the first address in that page (A3 to A0 = 0000b).

Bank mode : S2, S1, S0 is effective.
Combine mode : A8 is effective. S2 and S1 are Don't care
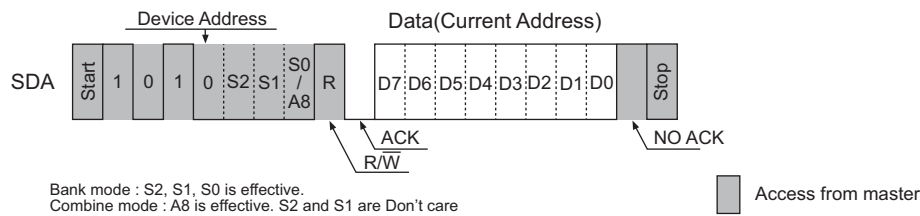
8-2. Random read

Random read is a mode in which any memory address is specified and its data read. The address is specified by a dummy write input.

First, when the EEPROM receives the 7-bit device address and write command code "0" following the start condition, it generates an acknowledge signal. It then receives the 8-bit word address, and generates an acknowledge signal. Through these operations, the word address is loaded into the address counter inside the EEPROM.

Next, the start condition is input again and the current read is initiated. This causes the data of the word address that was input using the dummy write input to be output. If, after the data is output, an acknowledge signal is not sent and the stop condition is input, reading is completed, and the EEPROM returns to standby mode.

Bank mode : S2, S1, S0 is effective.
Combine mode : A8 is effective. S2 and S1 are Don't care
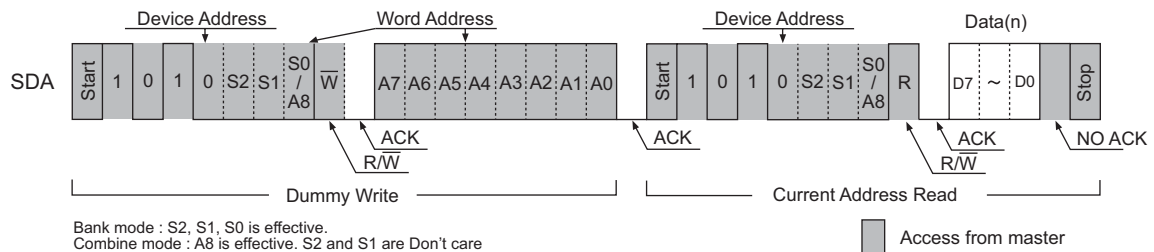
8-3. Sequential read

In this mode, the data is read continuously, and sequential read operations can be performed with both current address read and random read. If, after the 8-bit data has been output, acknowledge "0" is input and reading is continued without issuing the stop condition, the address is incremented, and the data of the next address is output.

If acknowledge "0" continues to be input after the data has been output in this way, the data is successively output while the address is incremented. When the last address is reached, it is rolled over to address 0, and the data continues to be read. As with current address read and random read, the operation is completed by inputting the stop condition without sending an acknowledge signal.

Bank mode : S2, S1, S0 is effective.
Combine mode : A8 is effective. S2 and S1 are Don't care
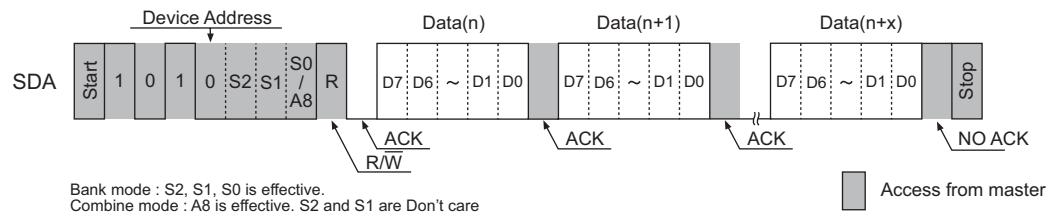
Application Notes

1) Software reset function

Software reset (start condition + 9 dummy clock cycles + start condition), shown in the figure below, is executed in order to avoid erroneous operation after power-on and to reset while the command input sequence. During the dummy clock input period, the SDA bus must be opened (set to high by a pull-up resistor). Since it is possible for the ACK output and read data to be output from the EEPROM during the dummy clock period, forcibly entering H will result in an overcurrent flow.

Note that this software reset function does not work during the internal write cycle.
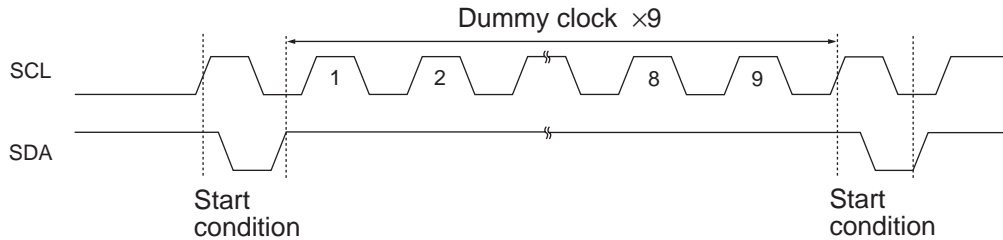
2) Pull-up resistor of SDA pin

Due to the demands of the I^2C bus protocol function, the SDA pin must be connected to a pull-up resistor (with a resistance from several kΩ to several tens of kΩ) without fail. The appropriate value must be selected for this resistance (R_{PU}) on the basis of the V_{IL} and I_{IL} of the microcontroller and other devices controlling this product as well as the V_{OL}–I_{OL} characteristics of the product. Generally, when the resistance is too high, the operating frequency will be restricted; conversely, when it is too low, the operating current consumption will increase.

R_{PU} maximum resistance

The maximum resistance must be set in such a way that the bus potential, which is determined by the sum total (I_L) of the input leaks of the devices connected to the SDA bus and by R_{PU}, can completely satisfy the input high level (V_{IH} min) of the microcontroller and EEPROM. However, a resistance value that satisfies SDA rise time t_R and fall time t_F must be set.

R_{PU} maximum value = $(V_{DD} - V_{IH})/I_L$

Example: When V_{DD}=3.0V and I_L= 2μA
R_{PU} maximum value = $(3.0V - 3.0V \times 0.8)/2\mu A = 300k\Omega$

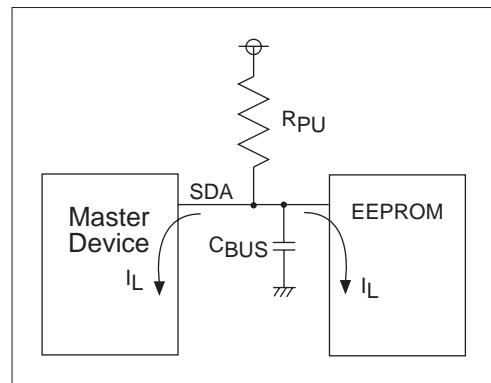R_{PU} minimum value

A resistance corresponding to the low-level output voltage (V_{OL} max) of EEPROM must be set.

R_{PU} minimum value = $(V_{DD} - V_{OL})/I_{OL}$

Example: When V_{DD}=3.0V, V_{OL} = 0.4V and I_{OL} = 1mA
R_{PU} minimum value = $(3.0V - 0.4)/1mA = 2.6k\Omega$

Recommended R_{PU} setting

R_{PU} is set to strike a good balance between the operating frequency requirements and power consumption. If it is assumed that the SDA load capacitance is 50pF and the SDA output data strobe time is 500ns, R_{PU} will be about R_{PU} = 500ns/50pF = 10kΩ.

3) Precautions when turning on the power

This product contains a power-on reset circuit for preventing the inadvertent writing of data when the power is turned on. The following conditions must be met in order to ensure stable operation of this circuit. No data guarantees are given in the event of an instantaneous power failure during the internal write operation.

Item	Symbol	V_{DD}=2.5 to 5.5V			unit
		min	typ	max	
Power rise time	t_{RISE}			100	ms
Power off time	t_{OFF}	10			ms
Power bottom voltage	V_{bot}			0.2	V
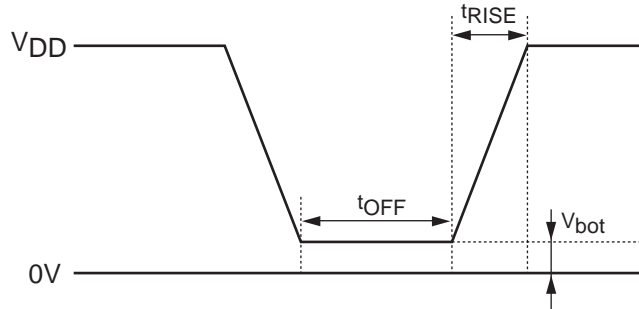
Notes:
1) The SDA pin must be set to high and the SCL pin to low or high.
2) Steps must be taken to ensure that the SDA and SCL pins are not placed in a high-impedance state.

A. If it is not possible to satisfy the instruction 1 in Note above, and SDA is set to low during power rise
After the power has stabilized, the SCL and SDA pins must be controlled as shown below, with both pins set to high.
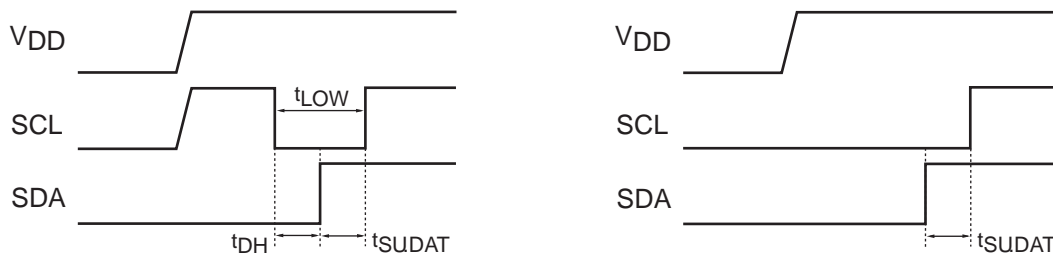
B. If it is not possible to satisfy the instruction 2 in Note above
After the power has stabilized, software reset must be executed.

C. If it is not possible to satisfy the instructions both 1 and 2 in Note above
After the power has stabilized, the steps in A must be executed, then software reset must be executed.

4) Noise filter for the SCL and SDA pins
This product contains a filter circuit for eliminating noise at the SCL and SDA pins. Pulses of 100ns or less are not recognized because of this function.

5) Function to inhibit writing when supply voltage is low
This product contains a supply voltage monitoring circuit that inhibits inadvertent writing below the guaranteed operating supply voltage range. The data is protected by ensuring that write operations are not started at voltages (typ.) of 1.3V and below.

6) Slave address setting
This product does not have a slave address pin, but holds the slave address S0, S1 and S2 information internally. At the default, the slave address of this product is set to S0 = 0, S1 = 0, S2 = 0. During device addressing, execute this slave address following the device code.

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7) Precautions when write protects operation.

Write to all memory areas is prohibited when the WP# pin of this product is set to the low level. The WP# pin must be held at the low level during the entire period from the start condition to the stop condition, and the following conditions must also be observed in order to ensure reliable write protect functions.

Parameter	Symbol	V_{DD}=2.5V to 5.5V			unit
		min	typ	max	
WP# set-up time	$t_{SU.WP}$	600	-	-	ns
WP# hold time	$t_{HD.WP}$	600	-	-	ns
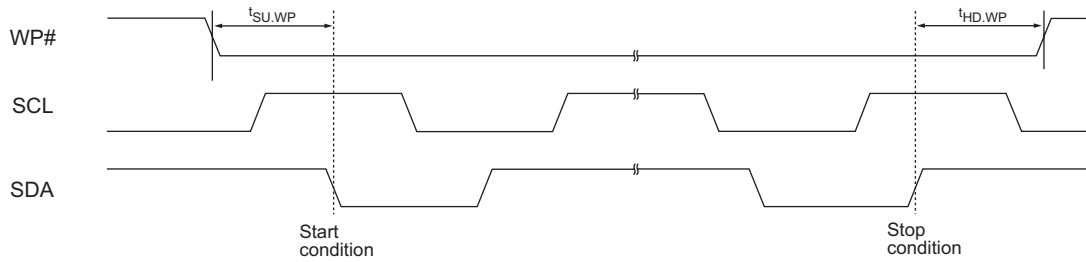
8) Precautions when changing the mode

These products selects bank mode operation or combine mode operation according to the COBM# pin status. Changing the COBM# pin status while this product is active (during access to Bank1 or Bank2, including during the write period) is prohibited.

The following conditions must be observed in order to ensure reliable access functions in each mode.

Parameter	Symbol	V_{DD}=2.5V to 5.5V			unit
		min	typ	max	
COBM# set-up time	$t_{SU.COBM}$	10	-	-	µs
COBM# hold time	$t_{HD.COBM}$	5	-	-	ms
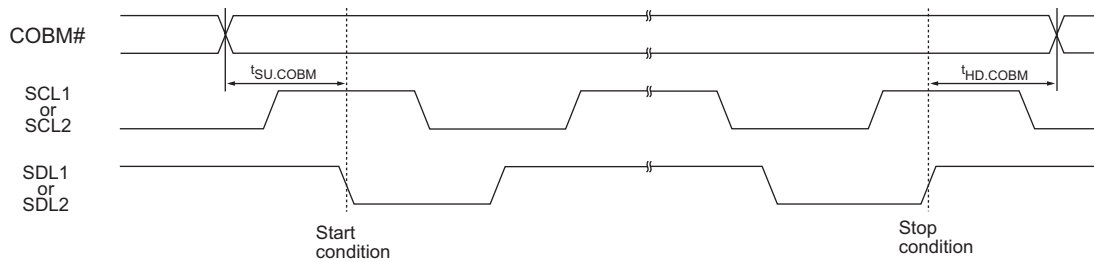
9) Writing with a ROM writer from the combine mode

This product enables two-bank configuration (2K bits + 2K bits) to be used as a pseudo-one-bank configuration (4K bits) by accessing the memory areas from the control port (SCLC, SDAC). As a result, data can be written using a ROM writer with the EEPROM serving as a regular 4K-bit EEPROM. Fix the port 1 and port 2 pins to high or low.

LE24CBK23MC

```
SCL2  □ 1 ●    8 □ VDD
SDA2  □ 2      7 □ WP#
COBM# □ 3      6 □ SCL1
GND   □ 4      5 □ SDA1
```

LE24C04x
(Standard 4k-bit EEPROM)

```
S0   □ 1 ●    8 □ VDD
S1   □ 2      7 □ WP
S2   □ 3      6 □ SCL
GND  □ 4      5 □ SDA
```
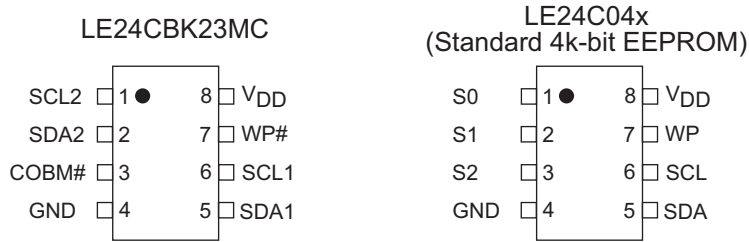
The Pin 3 (slave pin: S2) function of a regular 4K-bit EEPROM product is assigned to the COBM# pin of the LE24CBK23MC.

Combine mode is entered by setting the COBM# pin to the low level. In combine mode, the SCL2 and SDA2 pins are don't care (high level or low level or OPEN).

ROM writer connection example

LE24CBK23MC

```
(Don't care)
  { SCL2  □ 1 ●    8 □ VDD
  { SDA2  □ 2      7 □ WP#
    COBM# □ 3      6 □ SCL1
    GND   □ 4      5 □ SDA1
```

Connect to GND level

Combine mode
(From SCL1/SDA1)

	Device code			Slave Address			
1	0	1	0	SA2	SA1	A8	R/W̄

MSB ← Device Address word → LSB
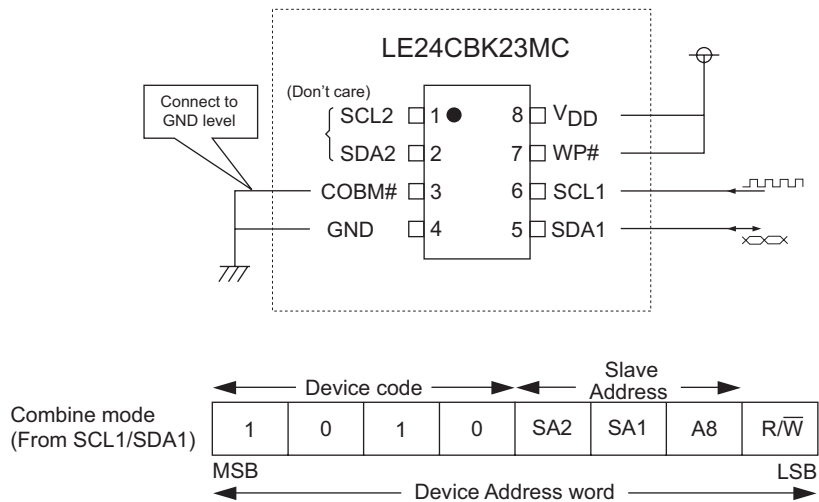
In combine mode, the slave address (SA2, SA1) is don't care, and any combination can be entered (SA2 = 1, SA1 = 1 or SA2 = 1, SA1 = 0 or SA2 = 0, SA1 = 1 or SA2 = 0, SA1 = 0).

Memory Area (4K-bit)

```
000h
   Bank1
   (2k-bit)      A8=0
0FFh
100h
   Bank2
   (2k-bit)      A8=1
1FFh
```
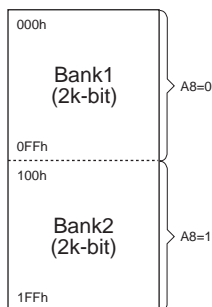
The MSB address in combined mode is A8. A8 is used to select the Bank1 or Bank2 area. Set A8 = 0 to control the Bank1 area, or A8 = 1 to control the Bank2 area.

10) System Configuration Image
   (HDMI System)

This product can support two HDMI ports simultaneously. Both ports can be accessed at the same time when performing read operations of the ports. All the data can be written together from a image processor into the areas allocated to the two ports from the control port in a single operation.
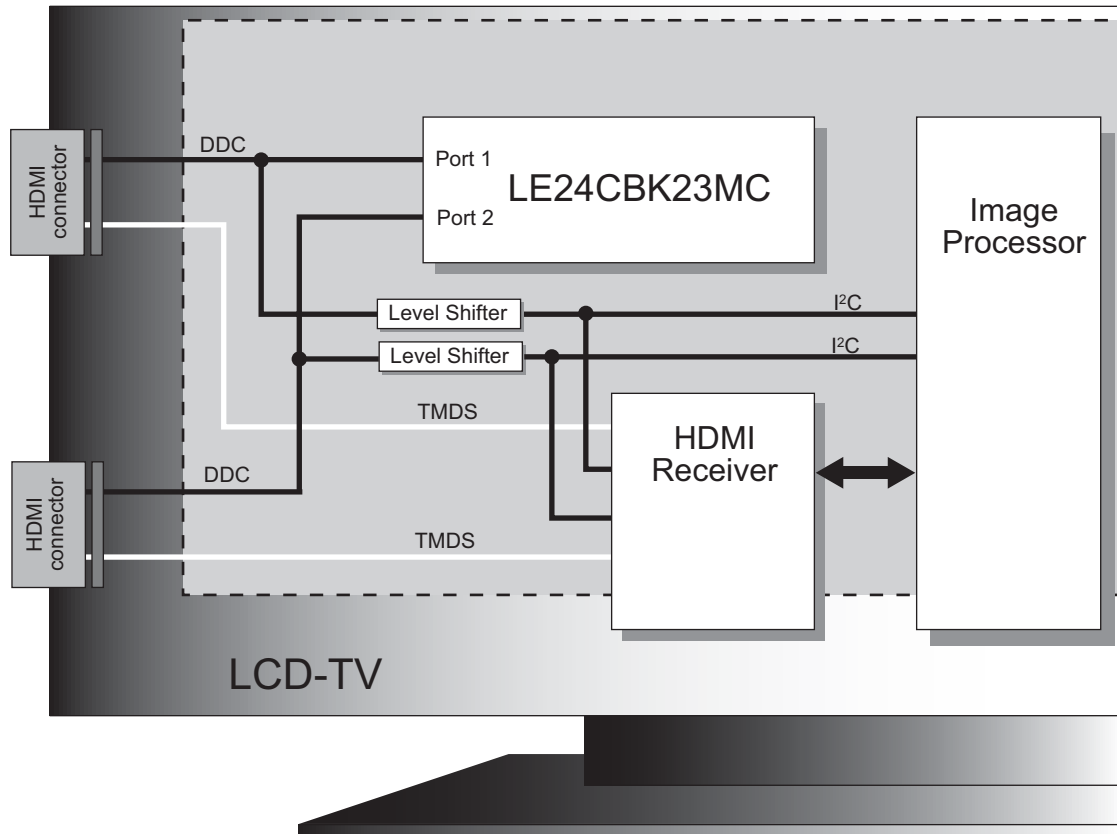
11) Peripheral Circuit Diagram
    Example of connection with HDMI receiver
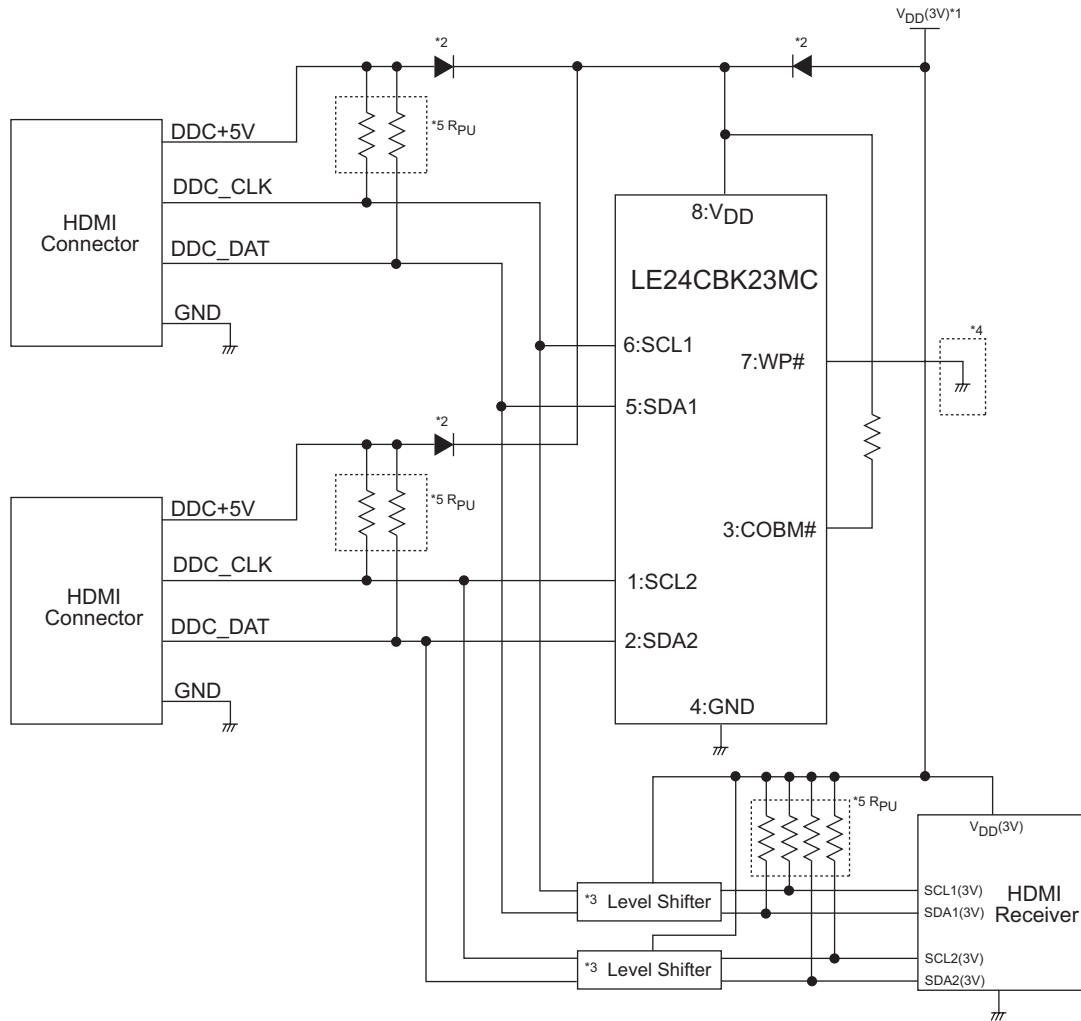
*1: System power supply (3V) for HDMI receiver, etc.

*2: Reverse-current preventing diode
    This device can be operated by supplying power from any of the connected HDMI connectors (DDC + 5V) or the system power supply (3V). However, the supply voltage must be set so that the voltage stepped-down by the reverse-current preventing diode is within the guaranteed operation voltage range of this device.

*3: Level shifter
    When connecting the 5V HDMI connector side with a 3V system, level shifters must generally be inserted. However, this is not necessary when the HDMI receiver supports 5V input signals.

*4: Write protection
    In general, use with HDMI applications assumes that this device is used as read-only after mounting. The write protection function is enabled to prevent write due to mistaken access, by setting the WP# pin to the ground level. When reconfiguration is required, write operation is enabled by connecting the WP# pin to the logic high level using a jumper, etc.

*5: Pull-up resistors for the I^2C and DDC interfaces.
    See item 2) in the Application Notes for the resistance value settings.

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- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.

Как с нами связаться

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